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Method and device for cutting single crystals, in addition to an adjusting device and a test method for determining a crystal orientation

Abstract

A method for the division of single crystals, in particular of GaAs, is provided in which a single crystal (1) to be cut into at least two parts and a cutting tool (2, 3; 8, 8a, 8b, 8c) are moved relative to one another in a direction of advancement (V) and wherein the single crystal (1) is oriented in such a way that a specified crystallographic orientation (K) lies in the cutting plane (T), characterised in that an angle (ρ) between the specified crystallographic direction (K) and the direction of advancement (V) is chosen in such a way that forces which act on the cutting tool during cutting in a direction at right angles to the cutting plane compensate one another.

(Fig 1)

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